WHAT IS CLAIMED IS:

1. An apparatus for polishing an object to be polished using a polishing pad having a polishing surface, the apparatus comprising:

a polishing table for supporting the polishing pad, the polishing table being configured to be rotatable;

a substrate holding unit configured to hold the object to be polished and press the object to be polished against the polishing pad;

a supplying device for supplying polishing liquid to the polishing surface in a state in which the supplying device is pressed against the polishing pad; and

a pressing mechanism configured to press the supplying device against the polishing pad, wherein

the supplying device includes:

a sidewall pressed against the polishing surface, the sidewall including a first wall on an upstream side in a rotating direction of the polishing table and a second wall on a downstream side in the rotating direction of the polishing table; and

a holding space surrounded by the sidewall and opened to the polishing surface, the holding space holding the polishing liquid and supplying the polishing liquid to the polishing surface, and

the pressing mechanism configured to respectively adjust pressing forces to the first wall and the second wall,

wherein the pressing mechanism comprises a plurality of pressing means each including a rod, and a pressing-posture adjusting mechanism configured to adjust a posture of the supplying device, and

the pressing-posture adjusting mechanism comprises a pressing means-side block fixed to the rods of the plurality of pressing means, and a supply device-side block fixed to the supply device and rotatably engaged with the pressing means-side block via a shaft, and when the supply device is placed on the polishing surface, the supply device-side block

rotates around the shaft with respect to the pressing means-side block such that the supply device is set in parallel to the polishing surface.

2. The apparatus according to claim 1, wherein the pressing mechanism includes a plurality of pressing units configured to press the supplying device and is configured to be capable of respectively adjusting the pressing forces to the first wall and the second wall by controlling pressing forces of the pressing units, and wherein the pressing units are configured by the rods.

3. The apparatus according to claim 2, wherein the pressing mechanism respectively adjusts the pressing forces to the first wall and the second wall to thereby discharge, with the first wall, used polishing liquid to an outside of the polishing pad and adjust, with the second wall, an amount of the polishing liquid on the polishing pad supplied from the holding space to the substrate holding unit side.

4. The apparatus according to claim 2, wherein the pressing mechanism respectively adjusts the pressing forces to the first wall and the second wall by the pressing mechanism to thereby collect, with the first wall, at least a part of used polishing liquid in the holding space and adjust, with the second wall, the amount of the polishing liquid on the polishing pad supplied from the holding space to the substrate holding unit side.

5. The apparatus according to any one of claims 1 to 4, wherein the first wall includes one or a plurality of first opening sections for collecting the polishing liquid on the polishing surface.

6. The apparatus according to claim 5, wherein each of the one or plurality of first opening sections has any shape and dimensions and is disposed in any position of the first wall.

7. The apparatus according to any one of claims 1 to 6, wherein the first wall includes one or a plurality of second opening sections for supplying the polishing liquid from the holding space to the polishing surface.

8. The apparatus according to claim 7, wherein each of the one or plurality of second opening sections has any shape and dimensions and is disposed in any position of the first wall.

9. The apparatus according to claim 8, wherein the first wall includes the plurality of second opening sections provided at different heights.

10. The apparatus according to any one of claims 1 to 9, wherein the second wall includes one or a plurality of third opening sections for supplying the polishing liquid from the holding space of the supplying device to the substrate holding unit side.

11. The apparatus according to claim 10, wherein each of the one or plurality of third opening sections has any shape and dimensions and is disposed in any position of the second wall.

12. The apparatus according to claim 11, wherein the second wall includes the plurality of third opening sections provided at different heights.

13. The apparatus according to any one of claims 1 to 12, wherein

the second wall includes a portion preceding other portions in the rotating direction of the polishing table in a plan view, and

a supply amount of the polishing liquid from the preceding portion is larger than a supply amount of the polishing liquid from the other portions.

14. The apparatus according to claim 13, wherein, in a plan view, any end portion side in a longitudinal direction of the second wall precedes other portions in the rotating direction of the polishing table.

15. The apparatus according to claim 13, wherein, in a plan view, a center side in the longitudinal direction of the second wall precedes other portions in the rotating direction of the polishing table.

16. The apparatus according to any one of claims 1 to 15, wherein the pressing means comprises a cylinder configured to drive the rod by fluid~~the pressing mechanism further includes a pressing-posture adjusting mechanism for adjusting a posture of the supplying device~~.

17. The apparatus according to any one of claims 1 to 16, wherein the pressing mechanism is configured to be capable of pressing the supplying device with different pressing forces in different parts in a longitudinal direction of the supplying device and/or different parts in a width direction of the supplying device~~polishing table~~.

18. The apparatus according to any one of claims 1 to 17, further comprising a polishing-liquid removing unit configured to remove used polishing liquid, the polishing-liquid removing unit being disposed between the substrate holding unit and the supplying device in the rotating direction of the polishing table.

19. The apparatus according to any one of claims 1 to 18, further comprising a temperature adjusting unit configured to adjust temperature of the polishing surface.

20. A method for polishing an object to be polished by rotating a polishing table attached with a polishing pad and pressing the object to be polished held by a substrate holding unit against the polishing pad, the polishing method comprising:

placing~~pressing~~ a supplying device on~~against~~ the polishing surface, the supplying device being surrounded by a sidewall and including a holding space for ~~the~~a polishing liquid opened to a polishing surface of the polishing pad, and rotating a supply device-side block fixed to the supply device around a shaft with respect to a pressing means-side block fixed to rods of a plurality of pressing means, so as to set the supply device in parallel to the polishing surface and press the supply device against the polishing surface by the rods of the plurality of pressing means;

bringing the polishing liquid into contact with the polishing surface of the polishing pad in the holding space; and

respectively adjusting, with the pressing means~~a pressing mechanism~~, pressing forces of sidewalls on an upstream side and a downstream side in a rotating direction of the polishing table against the polishing surface to thereby discharge, with the sidewall on the upstream side, used polishing liquid to an outside of the polishing pad and/or collect at least a part of the used polishing liquid in the holding space and adjust, with the sidewall on the downstream side, an amount of the polishing liquid on the polishing pad supplied from the holding space to the substrate holding unit side.

21. The polishing method according to claim 20, wherein the polishing liquid is supplied to a desired portion of the polishing surface by a desired amount by adjusting the pressing force of the sidewall on the downstream side against the polishing surface.

22. The polishing method according to claim 20 or 21, wherein the polishing liquid supplied from the holding space to the substrate holding unit side is adjusted to be the polishing liquid mainly present in groove sections of the polishing surface by adjusting the pressing force of the sidewall on the downstream side against the polishing surface.